ESIA
European
Semiconductor
Industry
Association

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FOR IMMEDIATE RELEASE

Bosch executive Michael Budde elected new President of ESIA

On 10 December 2025, the General Assembly of the European Semiconductor Industry Association (ESIA) gathered in Brussels, Belgium, to elect Michael Budde, President Mobility Electronics at *Bosch*, as the organisation's new President for the next two years. ESIA represents and promotes the common interests of the Europe-based semiconductor industry towards the European institutions and stakeholders. Mr Budde is succeeding *Infineon Technologies*' CEO Jochen Hanebeck.

Michael Budde has served as divisional chief executive since October 2022. His career within *Bosch* spans over two-and-a-half decades of leadership experience and garnered him comprehensive expertise of the automotive industry. Mr Budde had gathered insights in electrical drives, battery systems, and various sales & marketing roles, including an international assignment in the United States. Under his guidance, *Bosch* has strengthened its position in semiconductor-based solutions for consumer and mobility applications, leveraging his deep understanding in the automotive industry and a close collaboration with OEMs. He holds a degree in mechanical engineering from the Rheinische Fachhochschule (RFH) in Cologne, Germany

On his election, Mr Budde commented: "*I am honoured to be elected President of ESIA and want to sincerely thank the General Assembly for the trust they are putting in me. Semiconductors are at the heart of Europe's technological sovereignty and global competitiveness – truly an 'industry of industries'. Today, we face exciting opportunities and significant challenges: from scaling up manufacturing in foundational, advanced nodes and securing resilient supply chains to addressing talent shortages and sustainability requirements. Semiconductors are the backbone of technological innovation, AI, and the green transition, and Europe must accelerate its efforts to remain a leader in these critical areas.*"

The next years will be decisive for shaping Europe's semiconductor future, as institutions are presenting, negotiating, and adopting key legislative files, ranging from the EU's long-term budget, the Chips Act 2, and regulatory action on operation-critical chemicals. At the same time, the European semiconductor industry continues to engage with its partners worldwide to jointly spur innovation, secure competitiveness and prosperity, and push boundaries of what's technologically feasible. On the opportunities of his mandate, Mr Budde remarked: "*My priority – together with ESIA members – will be to strengthen collaboration across the ecosystem, put the customer in the in focus, ensure the successful implementation and evolution of the EU Chips Act, and foster innovation that supports both industrial growth and strategic autonomy. I am committed to leading this effort with transparency and ambition.*"

Michael Budde, President Mobility Electronics,
Robert Bosch GmbH

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About ESIA: *The European Semiconductor Industry Association (ESIA) is the voice of the semiconductor industry in Europe. Its mission is to represent and promote the common interests of the Europe-based semiconductor industry towards the European institutions and stakeholders in order to ensure a sustainable business environment and foster its global competitiveness. As a provider of key enabling technologies, the industry creates innovative solutions for industrial development, contributing to economic growth and responding to major societal challenges. Being ranked as the most R&D-intensive sector by the European Commission, the European semiconductor ecosystem supports approx. 200.000 jobs directly and up to 1.000.000 induced jobs in systems, applications and services in Europe. Overall, micro- and nano-electronics enable the generation of at least 10% of GDP in Europe and the world.*